

massa winbond sassas

SINGLE-CHIP, SINGLE-MESSAGE
VOICE RECORD/PLAYBACK DEVICE
6- TO 12-SECONDS DURATION



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#### 1. GENERAL DESCRIPTION

Winbond's ISD18B12 ChipCorder<sup>®</sup> is a new single-chip single-message record/playback device with a special TryMe feature. The user-selectable duration is from 6 to 12 seconds, with wide operating voltage ranging from 2.4V to 5.5V. Its sampling frequency, ranging from 4kHz to 8kHz, is externally controlled via resistor at Rosc pin. This device also includes microphone amplifier, anti-aliasing filter, multilevel storage array, smoothing filter and speaker amplifier. Two external resistors are used to adjust the microphone amplifier gain for the incoming signal. Thus, a minimum record/playback subsystem can be configured with a microphone, a speaker, several passive components, two push buttons, and a power source.

Recordings are stored into on-chip non-volatile memory, providing zero-power message storage. This unique, single-chip solution is made possible through Winbond's patented Multi-Level Storage technology. Voice and audio signals are stored directly into memory in their natural form, providing high-quality, solid-state voice reproduction. The device is automatically power down after each operation cycle with typical standby current,  $1\mu A$ . With the embedded Flash memory employed, data retention up to 100 years and typical 100,000 erase/record cycles can be reached.

#### 2. FEATURES

Supply voltage: 2.4V to 5.5V

• User-selected variable sampling frequency and duration via external resistor

| Sampling Frequency | 8 kHz  | 6.4 kHz  | 5.3 kHz | 4 kHz   |
|--------------------|--------|----------|---------|---------|
| Rosc               | 80 KΩ  | 100 ΚΩ   | 120 ΚΩ  | 160 ΚΩ  |
| Duration           | 6 secs | 7.5 secs | 9 secs  | 12 secs |

RECL : Level recording

• RECE: Edge-trigger, toggle on-off

• PLAYE : Edge-trigger, toggle on-off

PLAYL : Level playback or looping playback

LEDR : LED output for recording

LEDP: LED output for playback

FT: Feed-through microphone input to speaker outputs

Microphone amplifier gain: user control via two external resistors

 With feed-through enabled, record microphone signal into memory while feed-through path remains active

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Playback takes precedence over the Recording operation

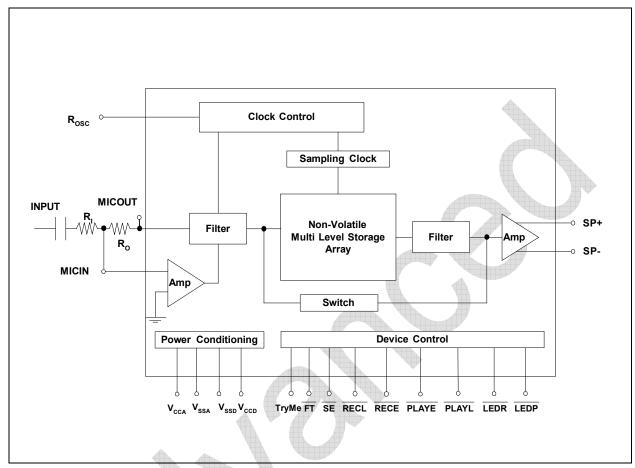
TryMe : TryMe special mode

Package option: die only

Temperature options: 0°C to +50°C



## 3. BLOCK DIAGRAM





## 4. PAD DESCRIPTION

| PAD NAME         | 1/0 | FUNCTION   |
|------------------|-----|--|
| V <sub>SSD</sub> | ı   | Digital Ground: Ground path for digital circuits.  |
| RECL             | I   | Level-Triggered Record: Low active input, Level-hold.  |
| PLAYE            | I   | Edge-Triggered Playback: Low active input, Edge-trigger, toggle on-off.  |
| PLAYL            | I   | Level-Triggered Playback: Low active input, Level-hold.  |
| RECE             | I   | Edge-Triggered Record: Low active input, Edge-trigger, toggle on-off.  |
| NC               |     | NC: No Connect   |
| NC               |     | NC: No Connect   |
| NC               |     | NC: No Connect   |
| NC               | -   | NC: No Connect   |
| MICIN            | I   | <b>Microphone Input</b> : The MICIN transfers input signal to the on-chip microphone amplifier.                          |
| NC               | -   | NC: No Connect   |
| MICOUT           | 0   | Microphone Output: Output of the microphone amplifier.   |
| NC               |     | NC: No Connect   |
| NC               | -   | NC: No Connect   |
| SP-              | 0   | SP-: The negative signal of the differential speaker outputs.  |
| V <sub>SSA</sub> | I   | Analog Ground: Ground path for analog circuits.  |
| SP+              | 0   | SP+: The positive signal of the differential speaker outputs.  |
| V <sub>CCA</sub> | I   | Power Supply: Power supply for analog circuits.  |
| Rosc             | I   | Oscillator Resistor: Connect an external resistor from this pin to $V_{\text{SSA}}$ to select the sampling frequency     |
| FT               | I   | Feed-Through (FT): Low active input, Level-hold, Feed-through microphone input to speaker outputs while in active state. |
| NC               |     | NC: No Connect   |
| NC               | H   | NC: No Connect   |
| TryMe            | 7   | TryMe Mode : High active input, Level-hold. A special operating mode.  |
| LEDP             | 0   | LED output for Playback: During playback, this output is Low.  |
| NC               |     | NC: No Connect   |
| SE               |     | Sound Effect: Low active input, Level-hold, optional beeping sound effect.   |
| V <sub>CCD</sub> | I   | Power Supply: Power supply for digital circuits.   |
| LEDR             | 0   | LED output for Recording: During recording, this output is Low.  |

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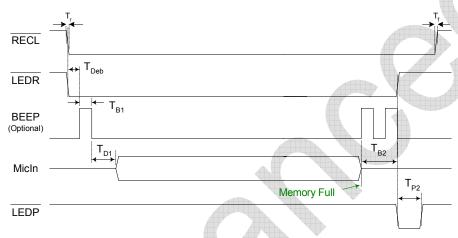
#### 5. FUNCTIONAL DESCRIPTION

For the following related operations, if SE is not enabled, then no beep sound is heard. Also, the timing diagrams may not be in direct proportional scale.

#### 5.1. Level-triggered Record (RECL) Operation:

- Recording starts from beginning of the memory and LEDR is on.
- Recording ceases whenever RECL returns to High or when end of memory is reached and LEDR is off.
- Then device will automatically power down.

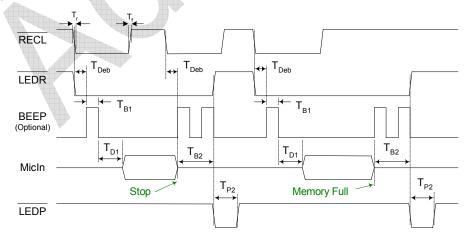
Fig. 1: Record-Level (RECL) function till memory full



#### 5.2. Edge-triggered Record (RECE)Operation:

- Recording starts from beginning of the memory and LEDR is on.
- Recording ceases whenever a subsequent trigger occurs at RECE or when end of memory is reached and LEDR is off.
- Then device will automatically power down.

Fig. 2: Record-Edge (RECE) function with on-off

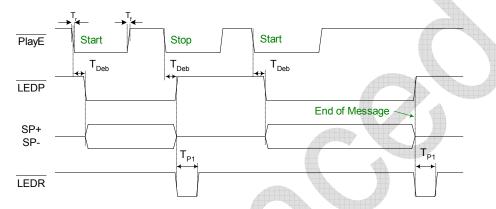




## 5.3. Edge-triggered playback (PLAYE) Operation :

- Playback starts from beginning of the memory and LEDP is on.
- Playback stops whenever end of message or a subsequent trigger occurs and LEDP is off.
- Then device will automatically power down.

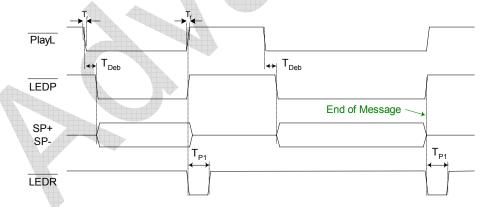
Fig. 3 : Playback–Edge (PLAYE) function



#### 5.4. Level- triggered playback (PLAYL) Operation:

- Playback starts from beginning of the memory and **LEDP** is on.
- Playback stops whenever an EOM marker is reached or PLAYL returns to High and LEDP is off.
- Then device will automatically power down.

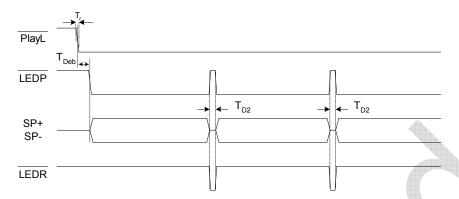
Fig. 4: Playback–Level (PLAYL) function



Holding PLAYL Low constantly will perform looping playback function.

Fig. 5: Looping playback function via PLAYL

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#### 5.5. Sound Effect ( SE ) Operation :

 Beeping feature for recording. Once active, one-beep indicates the start of recording and two-beep represents the end of recording.

#### 5.6. Microphone amplifier gain

 Two external resistors, R<sub>I</sub> and R<sub>O</sub>, are used to adjust the microphone amplifier gain with respect to the incoming signal.

#### 5.7. Playback (supersedes Record) Operation:

- Playback takes precedence over the Recording operation.
- If either PLAYE or PLAYL is activated during a recording cycle, the recording immediately ceases and playback of the just-recorded message performs accordingly.

#### 5.8. Feed-Through mode Operation:

- As FT is held Low, the input signal from MICIN will directly transmit to the speaker outputs.
- If either RECE is triggered or RECL is held Low simultaneously after FT is enabled, then input signal will be recorded into memory while the Feed-Through mode is still on.
- After FT is enabled, activating either PLAYE or PLAYL will first disable the feed-through path and play the recorded message. Once playback is completed, the feed-through feature resumes.

#### 5.9. LEDR Operation:

- LEDR stays on during recording.
- Also, LEDR pulses Low momentarily at the end of playback operation.

#### 5.10. LEDP Operation:

- LEDP stays on during playback.
- Also, LEDP pulses Low momentarily at the end of recording.

#### 5.11. Rosc Operation:

- When the  $R_{OSC}$  varies from 80 K $\Omega$  to 160 K $\Omega$ , the duration changes from 6 to 12 seconds accordingly.
- When R<sub>OSC</sub> resistor value is changed during playback, the tone of a recorded message will alter either faster or slower.

#### 5.12. Speaker Outputs

Both SP+ and SP- outputs can be used to drive an 8Ω speaker differentially. They are tri-state while
device is in power down status.



#### 5.13. TryMe Special Operation:

This is a special feature. When **TryMe** is High, TryMe is active. When **TryMe** is Low, TryMe is disabled. The enabling and disabling of this feature is merely permitted while the device is in power down status. Once **TryMe** is set, trigger on either **RECL** or **RECE** will initiate the TryMe operation sequence. While active, the device performs a combination of the following 3 operations sequentially: Record a new message and automatic playback the just-recorded message once, then delete the recorded message. Internal pull-up exists.

The details of each operation are described as follows:

- a) Recording:
  - The recording behavior follows the characteristics of the selected record pin, RECL or RECE.
  - While recording, the **LEDR** is on if an LED is connected appropriately.
- b) Playback:
  - Upon completion of recording, the device automatic plays the just-recorded message once and stops. During this operation, change of state on any control pins is prohibited.
  - While playback, the **LEDP** is on if an LED is connected appropriately.
- c) Erasure:
  - Upon completion of playback, the device will involuntary delete the recorded message. During this
    operation, change of state on any control pins is banned.

After completion of this TryMe operation, the device returns to standby state automatically. Once playback operation starts, any input on other controls is illegal.

As a summary, the TryMe mode starts in the following conditions:

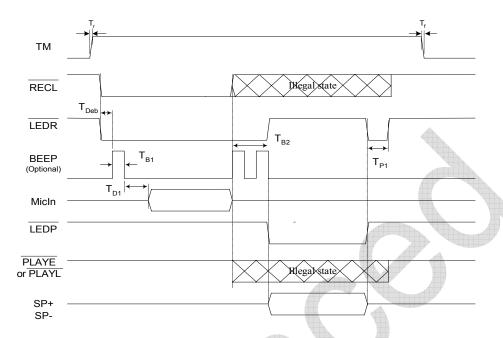
| Pin         | TryMe | RECL | RECE |
|-------------|-------|------|------|
| Logic Level | 1     | 0    | 1    |
|             | 1     | 1    | 0    |

Under no circumstances, while this special operation is in progress, neither the power is disturbed nor any change of state on other control pins are permitted. Otherwise, it may cause the device becoming malfunction.

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Fig 6: TryMe function via (TryMe + RECL)

# **Tables Winbond** =



#### 5.14. Power interruption

Any power interruption during an operation is strongly not recommended. If happened, it may result the
device becoming malfunction.

#### 5.15. Power-On to Playback Operation :

• If PLAYE or PLAYL is held at Low during power turns on, the device plays message accordingly with respect to which play control being employed.

#### 5.16. Power-On to Loop Playback Operation:

 If PLAYL is hardwired to ground permanently, once power is on, the device performs looping playback non-stop. This status will sustain unless power is turned off.

#### 5.17. Automatic Playback after Record Operation:

• If **LEDP** is connected to **PLAYE**, after a record operation, then the device will automatic play message once, then powers down.



#### 6. ABSOLUTE MAXIMUM RATINGS

## ABSOLUTE MAXIMUM RATINGS [1]

| CONDITION  | VALUE                                  |
|--|--|
| Junction temperature   | 150°C                                  |
| Storage temperature range                                    | -65°C to +150°C                        |
| Voltage applied to any pins                                  | $(V_{SS} - 0.3V)$ to $(V_{CC} + 0.3V)$ |
| Voltage applied to Input pins (current limited to +/-20 mA)  | $(V_{SS} - 1.0V)$ to $(V_{CC} + 1.0V)$ |
| Voltage applied to output pins (current limited to +/-20 mA) | $(V_{SS} - 1.0V)$ to $(V_{CC} + 1.0V)$ |
| V <sub>CC</sub> - V <sub>SS</sub>                            | -0.3V to +7.0V                         |

<sup>&</sup>lt;sup>[1]</sup> Stresses above those listed may cause permanent damage to the device. Exposure to the absolute maximum ratings may affect device reliability and performance. Functional operation is not implied at these conditions.

#### **6.1 OPERATING CONDITIONS**

#### **OPERATING CONDITIONS**

| CONDITION                                | VALUE          |
|--|----------------|
| Operating temperature range              | 0°C to +50°C   |
| Operating voltage (V <sub>CC</sub> ) [1] | +2.4V to +5.5V |
| Ground voltage (V <sub>SS</sub> ) [2]    | 0V             |

$$^{[1]}V_{CC} = V_{CCA} = V_{CCD}$$

$$^{[2]}$$
  $V_{SS} = V_{SSA} = V_{SSD}$ 



### 7. ELECTRICAL CHARACTERISTICS

#### 7.1. DC PARAMETERS

| PARAMETER  | SYMBOL              | MIN <sup>[2]</sup> | TYP <sup>[1]</sup> | MAX <sup>[2]</sup> | UNITS | CONDITIONS                              |
|--|---------------------|--------------------|--------------------|--------------------|-------|---|
| Input Low Voltage  | V <sub>IL</sub>     |                    |                    | 0.3xVcc            | V     |   |
| Input High Voltage   | V <sub>IH</sub>     | 0.7xVcc            |                    |                    | V     |   |
| Output Low Voltage   | $V_{OL}$            |                    |                    | 0.3xVcc            | >     | $I_{OL} = 4.0 \text{ mA}^{[3]}$         |
| Output High Voltage  | $V_{OH}$            | 0.7xVcc            |                    |                    | V     | $I_{OH} = -1.6 \text{ mA}^{[3]}$        |
| Standby Current  | I <sub>STBY</sub>   |                    | 1                  | 10                 | μA    | [4] [5]                                 |
| Record Current   | I <sub>REC</sub>    |                    |                    | 15                 | mA    | V <sub>CC</sub> = 5.5V                  |
| Playback Current   | I <sub>PLAY</sub>   |                    |                    | 15                 | mA    | V <sub>CC</sub> = 5.5V, no speaker load |
| Pull-up device for RECL, RECE, PLAYE, PLAYL, FT & TryMe pins | R <sub>PU1</sub>    |                    | 40                 |                    | kΩ    |   |
| Pull-up device for SE  | R <sub>PU2</sub>    |                    | 80                 |                    | kΩ    |   |
| Output Load Impedance  | R <sub>EXT</sub>    | 8                  |                    |                    | Ω     | Speaker load                            |
| MIC Input Voltage  | V <sub>IN</sub>     | 4                  |                    | 400                | mV    | Peak-to-peak                            |
| MIC Amplifier Gain   | A <sub>MicAmp</sub> | 0                  |                    | +34                | dB    | Depend on RO/RI                         |
| Gain from MIC to SP+/SP-                                     | A <sub>MSP</sub>    | +12                |                    | +46                | dB    | Depend on RO/RI                         |

#### Notes:

Typical values @  $T_A = 25^\circ$ ,  $V_{CC} = 5.5V$  and sampling frequency (Fs) at 8 kHz, unless stated.

All Min/Max limits are guaranteed by design, electrical testing and/or characterization. Not all specifications are 100 percent tested.

<sup>[3]</sup> LED output during recording.

<sup>&</sup>lt;sup>[4]</sup> V<sub>CCA</sub> and V<sub>CCD</sub> are connected together. Also, V<sub>SSA</sub> and V<sub>SSD</sub> are connected together.

<sup>[5]</sup> RECL, RECE, PLAYE, PLAYL, SE, FT and TryMe must be at V<sub>CCD</sub>. External components are biased under a separated power supply.



## 7.2. AC PARAMETERS

| CHARACTERISTIC           | SYMBOL            | MIN <sup>[2]</sup> | TYP <sup>[1]</sup> | MAX <sup>[2]</sup> | UNITS | CONDITIONS       |
|--------------------------|-------------------|--------------------|--------------------|--------------------|-------|------------------|
| Sampling Frequency       | Fs                | 4                  |                    | 8                  | kHz   | [3]              |
| Record Duration          | T <sub>REC</sub>  | 6                  |                    | 12                 | sec   | Depend on Fs [3] |
| Playback Duration        | T <sub>PLAY</sub> | 6                  |                    | 12                 | sec   | Depend on Fs [3] |
| Rising Time              | T <sub>r</sub>    |                    | 100                |                    | nsec  | [3]              |
| Falling Time             | T <sub>f</sub>    |                    | 100                |                    | nsec  | [3]              |
| Debounce Time            | T <sub>Deb</sub>  | 536k/FS            |                    |                    | msec  | [3] [4]          |
| Beep Duration            | T <sub>B1</sub>   |                    | 512k/FS            |                    | msec  | [3] [4]          |
| Beep-Beep Duration       | T <sub>B2</sub>   |                    | 1536k/FS           | 4                  | msec  | [3] [4]          |
| Delay to start recording | T <sub>D1</sub>   |                    | 1552k/FS           |                    | msec  | [3] [4]          |
| Delay during looping     | T <sub>D2</sub>   |                    | 1k/FS              |                    | msec  | [3] [4]          |
| LEDR Pulse Low Time      | T <sub>P1</sub>   |                    | 1024k/FS           |                    | msec  | [3] [4]          |
| LEDP Pulse Low Time      | T <sub>P2</sub>   |                    | 1280k/FS           |                    | msec  | [3] [4]          |

#### Notes:

- Conditions are  $V_{CC}$  = 5.5V and  $T_A$  = 25°C, unless specified.
- All Min/Max limits are guaranteed by design, electrical testing and/or characterization. Not all specifications are 100 percent tested.
- The value changes accordingly to the  $F_S$  applied. Also, the internal oscillator may vary as much as  $\pm 10\%$  over the operating temperature and voltage ranges.

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<sup>[4]</sup> k=1000





#### 8. TYPICAL APPLICATION CIRCUIT

The following typical application examples on ISD18B12 series are for references only. They make no representation or warranty that such applications shall be suitable for the use specified. Each design has to be optimized in its own system for the best performance on voice quality, current consumption, functionalities and etc. It's customer's obligation to confirm the design on all the functionalities of their end-products.

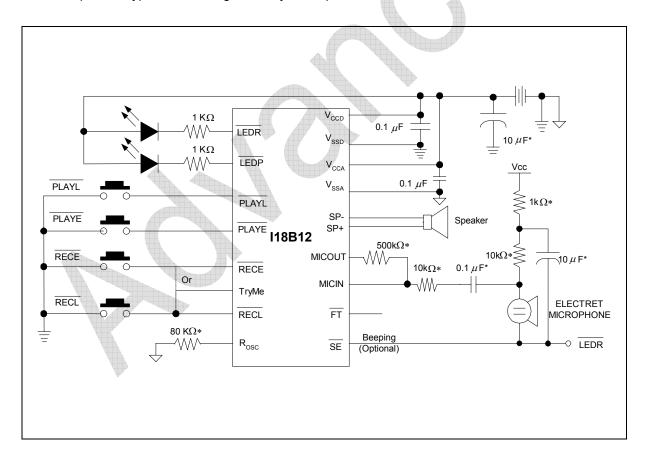
In addition, the below notes apply to the following application examples:

\* The suggested values are for references only. Depending on system requirements, they must be fine tuned for best performance.

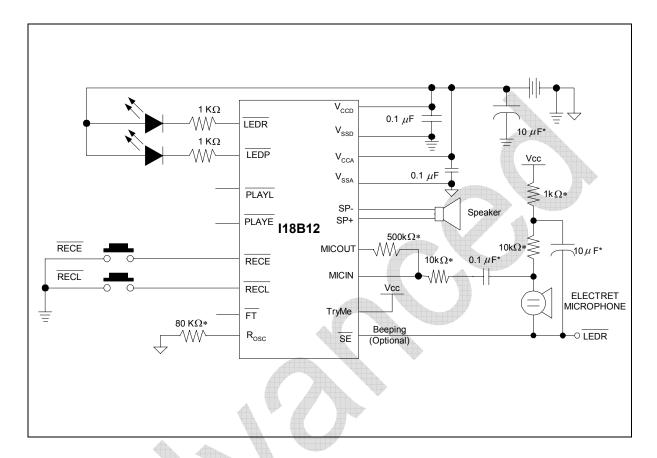
It is important to have a separate path for each ground and power back to the related terminals to minimize the noise. Besides, the power supplies should be decoupled as close to the device as possible.

Also, it is crucial to follow good audio design practices in layout and power supply decoupling. See recommendations in Application Notes from our websites.

Example #1: Typical Recording and Playback operations



Example #2: TryMe feature



#### **Good Audio Design Practices**

Winbond's ChipCorder are very high-quality single-chip voice recording and playback devices. To ensure the highest quality voice reproduction, it is important that good audio design practices on layout and power supply decoupling are followed. See Application Information links below for details.

#### **Good Audio Design Practices**

http://www.winbond-usa.com/products/isd\_products/chipcorder/applicationinfo/apin11.pdf

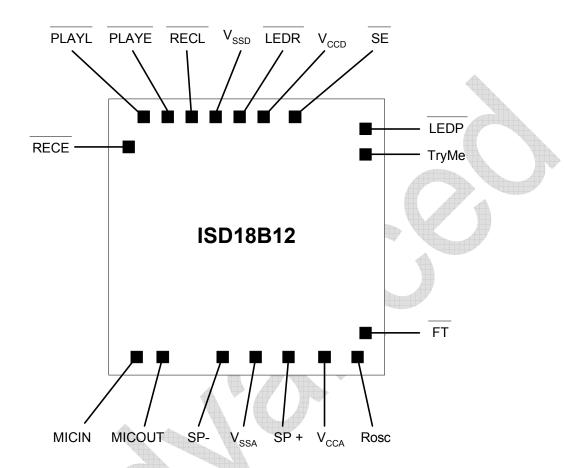
#### **Single-Chip Board Layout Diagrams**

http://www.winbond-usa.com/products/isd\_products/chipcorder/applicationinfo/apin12.pdf

It is strongly recommended that before any design or layout project starts, the designer should contact Winbond Sales Rep for the most update technical information.



## 9. DIE INFORMATION

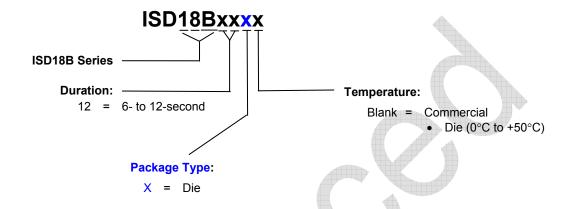


Contact Winbond Sales Representatives for information.



#### 10. ORDERING INFORMATION

## **Product Number Descriptor Key**



When ordering, please refer to the following part numbers that are supported in volume for this product series. Consult the local Winbond Sales Representative or Distributor for availability information.

| Package | Part Number | Ordering Number | Comments |
|---------|-------------|-----------------|----------|
| Die     | ISD18B12X   | I18B12X         |          |

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For the latest product information, access Winbond's worldwide website at <a href="http://www.winbond-usa.com">http://www.winbond-usa.com</a>



## 11. VERSION HISTORY

| VERSION | DATE        | DESCRIPTION          |  |  |  |
|---------|-------------|----------------------|--|--|--|
| A0      | May 2007    | Pre-released version |  |  |  |
| A1      | August 2007 | Initial revision     |  |  |  |





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